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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/769,554	01/30/2004	Chien-Min Sung	21154.DIV	5868
7590 05/03/2005				
M. Wayne Western THORPE NORTH & WESTERN, LLP P.O. Box 1219 Sandy, UT 84091-1219			EXAMINER PIZARRO CRESPO, MARCOS D	
			ART UNIT 2814	PAPER NUMBER

DATE MAILED: 05/03/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

# Office Action Summary

Application No.

10/769,554

Applicant(s)

SUNG, CHIEN-MIN

Examiner

Marcos D. Pizarro-Crespo

Art Unit

2814

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

## Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

## Status

- 1) ☒ Responsive to communication(s) filed on 20 April 2005.
- 2a) ☐ This action is FINAL. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

## Disposition of Claims

- 4) ☒ Claim(s) 1-30 is/are pending in the application.
- 4a) Of the above claim(s) 2,3 and 22-30 is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 1 and 4-21 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☒ Claim(s) 1-30 are subject to restriction and/or election requirement.

## Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on \_\_\_\_\_ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

## Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some \* c) ☐ None of:
- ☐ Certified copies of the priority documents have been received.
  - ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  - ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
- \* See the attached detailed Office action for a list of the certified copies not received.

## Attachment(s)

- |  |   |
|--|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892)                        | 4) <input type="checkbox"/> Interview Summary (PTO-413)                     |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)               | Paper No(s)/Mail Date. _____  |
| 3) <input checked="" type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152) |
| Paper No(s)/Mail Date <u>1/30/2004</u> .   | 6) <input type="checkbox"/> Other: _____                                    |

Attorney's Docket Number: 21154.DIV

Filing Date: 1/30/2004

Claimed Priority Date: 10/11/2002 (Divisional of 10/270,018)

Applicant(s): Sung

Examiner: Marcos D. Pizarro-Crespo

### **DETAILED ACTION**

This Office action responds to the election filed on 4/20/2005.

#### ***Election/Restrictions***

1. Applicant's election without traverse of species 3, as it was outlined in the Office action mailed 3/17/2005, is acknowledged. In the reply filed on 4/20/2005, the applicant indicated that claims 2, 3, 24, and 25 read on the elected species.
2. As set forth in the previous Office action, and indicated by the applicant in his reply, species 1-3 read on a method of bonding diamond particles, whereas species 4-6 read on a method of sintering diamond particles. Although the applicant indicates that claims 22, 23, and 26-30 read on elected species 3, these claims are directed to species 4-6, reading on a method of sintering diamond particles (see, e.g., claim 22 and claim 26/II.6-8).
3. Accordingly, claims 2, 3, and 22-30 are withdrawn from further consideration pursuant to 37 CFR 1.142(b) as being drawn to a nonelected species, there being no allowable generic or linking claim.

***Claim Rejections - 35 USC § 102***

4. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

5. Claims 1, 4, 11-14, 16, 17, 19, and 20 are rejected under 35 U.S.C. 102(e) as being anticipated by Hall (US 2002/0023733).

6. Regarding claim 1, Hall shows all aspects of the claimed invention including a method of making a diamond composite heat spreader comprising the steps of:

- Providing a first plurality of diamond particles having a first average mesh size (see, e.g., par.0018/II.13)
- Packing the diamond particles such that each diamond particle is substantially in contact with at least one other diamond particle (see, e.g., par.0022/II.29-37)
- Providing an interstitial material (see, e.g., par.0029)
- Bonding the packed diamond particles with the interstitial material such that the interstitial material at least partially fills any voids between the packed diamond particles (see, e.g., par.0025/II.1-8)

7. Regarding claim 4, Hall infiltrates the interstitial material to perform the bonding step (see, e.g., par.0029).

8. Regarding claim 11, Hall shows the diamond particles contacting one another sufficiently to provide a continuous diamond-to-diamond path to substantially each of the plurality of diamond particles (see, e.g., par.0022/II.53-56 and par.0035/II.9-10).
9. Regarding claim 12, Hall shows the method further comprising the steps of:
  - Providing a porous ceramic material prior to the step of bonding
  - Placing the ceramic material adjacent to the packed diamond particles prior to the step of bonding
10. Regarding claim 13, Hall shows the ceramic material comprising 100% WC.
11. Regarding claim 14, Hall shows the step of bonding is performed at a pressure between about 4GPa and about 6GPa.
12. Regarding claims 16, 17, and 19, Hall shows the interstitial material including a Fe alloy.
13. Regarding claim 20, Hall shows the interstitial material made from Al.

***Claim Rejections - 35 USC § 103***

14. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

15. Claims 1, 4-6, 16-18, and 21 are rejected under 35 U.S.C. 103(a) as being unpatentable over Sung (US 6039641) in view of Nishibayashi (JP 09-312362).

16. Regarding claim 1, Sung shows most aspects of the instant invention including a method of making a diamond composite comprising the steps of:

- Providing a first plurality of diamond particles having a first average mesh size (see, e.g., fig. 7B)
- Packing the diamond particles such that each diamond particle is substantially in contact with at least one other diamond particle (see, e.g., fig. 7B)
- Providing an interstitial material (see, e.g., col.14/ll.25-35)
- Bonding the packed diamond particles with the interstitial material such that the interstitial material at least partially fills any voids between the packed diamond particles (see, e.g., col.14/ll.35-40 and col.15/ll.51-61)

Sung, however, fails to teach that the diamond composite may be used as a heat spreader. Nishibayashi, on the other hand, teaches that thermal energy is usually transmitted faster in diamond than in any other material (see, e.g., par. 0003). Moreover, diamond has a thermal expansion rate lower than ordinary semiconductor materials (see, e.g., par. 0003). Heat spreaders consisting of diamond composites similar to one of Sung have superior applicability (see, e.g., par. 0032). They can be used, for example, to reduce warping due to thermal expansion differences between the spreader and a semiconductor (see, e.g., par. 0032).

It would have been at the time of the invention to one of ordinary skill in the art to use Sung's diamond composite to make a heat spreader, as suggested by Nishibayashi, to quickly transmit heat away from a heat source.

17. Regarding claim 4, Sung infiltrates the interstitial material to perform the bonding step (see, e.g., col.15/ll.51-61).

18. Regarding claim 5, Sung teaches that the infiltration is performed at a temperature below about 1,100°C (see, e.g., col.14/ll.32 and col.15/ll.1-10).

19. Regarding claim 6, Sung teaches that the infiltration is performed in a vacuum furnace at a pressure below about  $10^{-3}$  torr (see, e.g., col.13/ll.16-24).

20. Regarding claims 16-18, Sung teaches the interstitial material including a Ni-Cr-B alloy (see, e.g., col.14/ll.66).

21. Regarding claim 21, Sung teaches the interstitial material including a Si-Ni alloy (see, e.g., col.15/ll.5).

22. Claims 1, 7-10, and 15 are rejected under 35 U.S.C. 103(a) as being unpatentable over Chen (US 5096465) in view of Nishibayashi.

23. Regarding claim 1, Chen shows (see, e.g., fig. 2) most aspects of the instant invention including a method of making a diamond composite comprising the steps of:

- Providing a first plurality of diamond particles **10** having a first average mesh size (see, e.g., col.6/ll.23)
- Packing the diamond particles **10** such that each diamond particle is substantially in contact with at least one other diamond particle (see, e.g., fig.2)
- Providing an interstitial material **18** (see, e.g., fig. 2)

- Bonding the packed diamond particles with the interstitial material such that the interstitial material at least partially fills any voids between the packed diamond particles (see, e.g., col.8/ll.34-43)

Chen, however, fails to teach that the diamond composite may be used as a heat spreader. Nishibayashi, on the other hand, teaches that thermal energy is usually transmitted faster in diamond than in any other material (see, e.g., par. 0003). Moreover, diamond has a thermal expansion rate lower than ordinary semiconductor materials (see, e.g., par. 0003). Heat spreaders consisting of diamond composites similar to one of Sung have superior applicability (see, e.g., par. 0032). They can be used, for example, to reduce warping due to thermal expansion differences between the spreader and a semiconductor (see, e.g., par. 0032).

It would have been at the time of the invention to one of ordinary skill in the art to use Chen's diamond composite to make a heat spreader, as suggested by Nishibayashi, to quickly transmit heat away from a heat source.

24. Regarding claim 7, Chen teaches that the step of packing further comprises packing diamonds to over 50% by volume of the composite prior to providing the interstitial material (see, e.g., col.7/ll.63).

25. Regarding claim 8, Chen teaches that prior to the step of providing an interstitial material, the method further comprises the step of adding a second plurality of diamond particles having a second average mesh size, which is smaller than the first mesh size, to the packed diamond particles such that the second plurality of diamond particles at least partially fill in the voids between the larger particles to produce a packed collection



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of diamond between about 50% and about 80% by volume of diamond (see, e.g., col.7/II.35-64)

26. Regarding claims 9 and 10, Chen teaches the second mesh-size particles having a diameter of between about  $1/10^{\text{th}}$  and about  $1/5^{\text{th}}$  the diameter of the first mesh-size particles (see, e.g., col.7/II.44-45).

27. Regarding claim 15, Chen teaches the diamond particles having a size of from about 400 mesh to about 18 mesh (see, e.g., col.6/II.25).

### ***Conclusion***

28. Papers related to this application may be submitted directly to Art Unit 2814 by facsimile transmission. Papers should be faxed to Art Unit 2814 via the Art Unit 2814 Fax Center. The faxing of such papers must conform to the notice published in the Official Gazette, 1096 OG 30 (15 November 1989). The Art Unit 2814 Fax Center number is **(703) 872-9306**. The Art Unit 2814 Fax Center is to be used only for papers related to Art Unit 2814 applications.

29. Any inquiry concerning this communication or earlier communications from the examiner should be directed to **Marcos D. Pizarro-Crespo** at **(571) 272-1716** and between the hours of 9:30 AM to 8:00 PM (Eastern Standard Time) Monday through Thursday or by e-mail via [Marcos.Pizarro@uspto.gov](mailto:Marcos.Pizarro@uspto.gov). If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy, can be reached on (571) 272-1705.

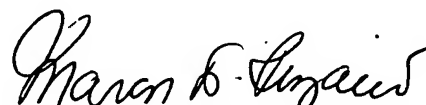
30. Any inquiry of a general nature or relating to the status of this application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status

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information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

31. The following list is the Examiner's field of search for the present Office Action:

Field of Search	Date
U.S. Class/Subclass(es): 438/15,25,26,51,55,64,105,106,122,584, FOR413	4/26/05
Other Documentation: PLUS Analysis	4/26/05
Electronic Database(s): EAST (USPAT, EPO, JPO)	4/26/05

  
**Marcos D. Pizarro-Crespo**

Patent Examiner

Art Unit 2814

571-272-1716

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